

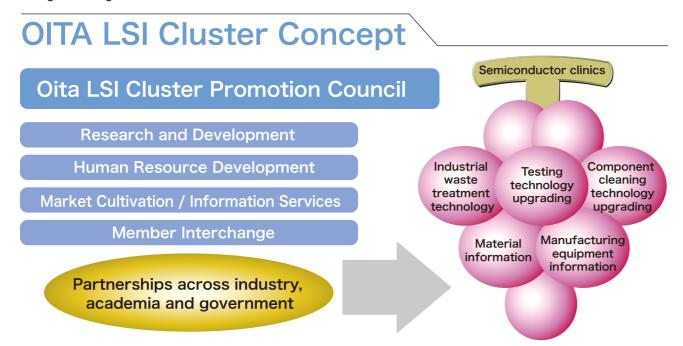




- Oita LSI Cluster's Concept
- Oita LSI Cluster's Vision
- Companies Regional Map
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OITA LSI Cluster Concept

The OITA LSI Cluster concept was formulated with the aim of generating more dynamic industrial activity in Oita Prefecture and achieving community and enterprise development and revitalization through both collaboration and competition. Oita LSI Cluster Promotion Council, established in April 2005, seeks to develop clusters of locally-based enterprises and major firms that have established operations in the prefecture, and utilize their technological strengths to create a 21st-century hub for semiconductor production that is internationally competitive in terms of quality, cost and turnaround time. This task involves the development of networks bringing together partners from industry, academia and government, and strategic initiatives to further integrate our prefecture's advanced manufacturing technologies.



The core element of the Oita LSI Cluster concept is engagement with the testing technologies (evaluation processes) essential to the manufacture of semiconductors. We aim to create a "semiconductor clinic" that delivers solutions based on scientific diagnosis and systematic technology development, accumulates and disseminates information and the results of impartial evaluation, and offers counseling as appropriate. To this end, we are implementing a range of specific initiatives around the four functional pillars of Research and Development, Human Resource Development, Market Cultivation / Information Supplement, and Member Interchange.

The acronym "LSI" used in the concept's title stands for the Large Scale Integrated circuits in semiconductors, but also incorporates the idea of Large Scale Integration of semiconductor-related enterprises in Oita prefecture for the purpose of advancing industrial activity.



OITA LSI Cluster Projects

Oita LSI Cluster Promotion Council has instituted a medium-range vision formulated primarily through its Planning Committee in the 2008 fiscal year.

OITA LSI Cluster Medium-Range Vision

Slogan

Importing global information, exporting Oita's innovations!

OITA LSI Cluster Concept

Research and Development

Generating new world-leading technologies.

Human Resource Development

Cultivating Human Resource of global standard.

Market Cultivation / Information Services

Gathering and providing information on technologies and needs of customers worldwide.

Member Interchange

Fostering businesspeople of global standard.

The specialist divisions for Research and Development, Human Resource Development, Market Cultivation / Information Services, and Member Interchange are each pursuing specific initiatives under the following sub-themes (strategies) developed in line with the medium-range vision.

Research and Developmen

- Realizing successful case models for business · linkage and development of new technologies.
- 2. Proposing developments in screening and evaluation systems.
- 3. Organizing mid-term reporting sessions and performance briefings for working groups.
- 4. Market research and market development assistance in relation to research themes.
- Research and development for productivity improvements, etc.
 Periodical information exchange with the
- Human Resource Development
- Cultivating and developing engineers with broad outlooks.
- 2. Operating projects led by working groups.
- 3. Augmenting training for technical personnel based on the needs of member enterprises.
- 4. Bolstering partnerships with universities, etc.
- 5. Engaging expert instructors from other organizations.
- 6. Expanding basic education and training for new personnel.
- 7. Supporting the maintenance of employment opportunities.

Market Cultivation / Information Services

- 1. Surveys and research on Joint tendering and other business models
- 2. Formulating systems for self-diagnosis of commercial position.
- 3. Increasing knowledge-gathering and provision of information to member enterprises.
- 4. Supporting business matching.
- 5. Bolstering information dissemination functions.

ember Interchange

- Organizing meetings for interaction among

 1. top-level executives from both within and beyond the prefecture.
- 2. Exchange and network-building with clusters in other regions and beyond Japan.
- 3. Collaboration with the Kyushu Semiconductor Industries and Technology Innovation Association.

Oita Prefecture Semiconductor Affiliated Companies Regional Map

Information current as of August 1, 2011



						Current as of August 1, 2011
Region No.	Region	No.	Company Name Agawa Mekki Inc. Industrial Park	Telephone 097-558-3758	Postal Code 870-0138	Address 3-2-18 Harukawa, Oita City
		2	Adachi Chemical Plants Co., Ltd.			1316-1 Tanegu Dainoue, Oita City
		3	Advantest Corporation		870-0919	3-8 Shinsakae Machi, Oita City
		4	Aberuf Inc.	097-537-3811	870-0037	Astion Kasuga #610, 6-6 Higashi-Kasuga-machi, Oita City
		5 6	Ulvac Techno Co., Oita CS Center Ishii Tool & Engineering Corp.			1-12-41 Aosaki, Oita City 2-5-60 Higashi Omichi, Oita City
		7	InfoWave, Inc.			Coop Nakamura, 1F, 2-11-18 Nagahama, Oita City
		8	Willtec Kyushu Co., Oita Support Center	097-513-2488	870-0034	Oita Center Bldg., 8F, 3-1-1 Miyako-machi, Oita City
		9	Ueki Corporation, Oita Offices	097-520-5880	870-0125	4353 Oaza Matsuoka, Oita City
		10	SS-Avenue Co, Ltd.	097-573-3335	870-0037	Oita Sofia Plaza Bldg. 4F, 17-19 Higashi Kasuga Machi, Oita City
			SMC Corporation, Oita Branch Office S-Craft Co., Ltd.	097-558-1807		4-6 Hiyoshi Machi, Oita City 1-1-5 Tsunoko Minami, Oita City
			STK Technology Co., Ltd.	097-527-2161		2468-10 Oaza Misa, Oita City
			Espec Kyushu Corp., Oita Branch	097-551-7343	870-0921	4-4-38 Hagiwara, Oita City
			Eto Manufacturing Co., Ltd.	097-521-1834	870-0145	4-7 Otozu Machi, Oita City
			NYS Precision Co., Ltd., Oita Factory			1-8-28 Aosaki, Oita City
			Oita General Service Co. Oita Device Technology Co., Ltd.			2200 Oaza Tsurusaki, Oita City 1660 Oaza Notsuharu, Oita City
			Otsuka Diesel Co., Ltd.	097-558-9271		1-1-32 Nishi Shinchi, Oita City
			ODDS/Oita Device Design Support	097-543-3293	870-0874	3-4-3 Nijigaoka, Oita City
		21	Kamimaru Co., Ltd., Kyushu Offices			1-12-14 Aosaki, Oita City
		22	Kawanodenki Corporation	097-544-3131		8-33 Tamuro Machi, Oita City
		23	Kansetsu Co., Oita Offices Kyushu Yozai Co.			1-7-23 Yokota, Oita City In the Oita Refinery Grounds, 1-1 Ichinosu, Oita City
		25	Kuritec Service Co., Oita Offices			11-5-24 Aosaki, Oita City
0	Oita City	26	Krone Co., Ltd.	097-521-2988	870-0133	686-1 Katsuragi, Oita City
•	Oita City	27	Copan Co., Ltd.			1-5-5 Mitugawa Shimo, Oita City
		28	Sard Electron Co. Ltd.			5-12-12 Shimogori Minami, Oita City
			Zynas Corporation Shell Electronics Co., Ltd.			11-22 Kotobuki Machi, Oita City 1-12-18 Aosaki, Oita City
			Suzuki Co., Ltd.			818-1 Oaza Kei, Oita City
		32	Sumika Chemical Analysis Service, Ltd. Business Headquarters, Oita Business Division	097-523-1181	870-0106	2200 Oaza Tsurusaki, Oita City
			Threedyne Corporation, Oita Service Center	097-574-4115	870-0125	8205-5 Oaza Matsuoka, Oita City
			Daiso Co. Takaki Tools & Materials Co., Ltd.			2995-5 Oaza Katashima, Oita City 3113-7 Oaza Shimogori, Oita City
		36	Tani Kogyo Co., Ltd.			1-14-23 Aosaki, Oita City
		37	TEC Engineering Corporation			1212-150 Oaza Ichigi, Oita City
			Toshiba Information Systems Technology, Inc.	097-524-6161	870-0197	Toshiba Oita Factory, 3500 Oaza Matsuoka, Oita City
		39	Toshiba Semiconductor & Storage Products Company			3500 Oaza Matsuoka, Oita City
		40	Tobu Kaihatsu Co., Ltd. Todaka Corp.			658-1 Oaza Sakomaru Yama, Oita City 1-3-21 Aosaki, Oita City
		L	Nittetsu Oita Techno Support Co., Ltd.			1 Oaza Nishinosu, Oita City
		ļ	Nippon Express, Oita Airport Branch			1-2-5 Toyomi, Oita City
		44	Micronics Japan Co., Ltd., Oita Technology Laboratory	097-596-7220	870-1117	2-5-1 Takae Nishi, Oita City
		45	Neos Company Limited, Oita Precision Workshop	097-527-3500	870-0278	1-6-10 Aosaki, Oita City
			Network Co., Ltd. Britec Co., Ltd.			Sakura Bldg. 3F, 6-15 Haru Shinmachi, Oita City 1-2-6 Mukaibaru Nishi, Oita City
			Pleson LLC			United Suehiro Bldg 3F, 1-5-16 Suehiro Machi, Oita City
			Horiba Techno Service Co., Ltd., Oita Service Station	097-551-3982	870-0921	Tsuruha Bldg. 1F, 2-2-37 Hagiwara, Oita City
			Mobile Create Co., Ltd.	097-514-3720	870-0804	No. 4, Miyuki Machi, Oita City
		51	U.S.I Corp., Oita Offices			2-19 Hanazuru, Oita City
2	Rennu City		YAC Co., Ltd., Photovoltaics Division (Oita Factory) Kyushu Partner's Inc.			543-3 Tsujiharu, Oita City 2-1 Souen Cho, Beppu City
-	Берра Опу	54	Shimada Electronics Works Co., Ltd.			512 Kaku, Nakatsu City
8	Nakatsu	55	Shinyei Technology Co., Ltd., Oita Factory		871-0101	311-10 Sanko Moriyama, Nakatsu City
9	City		T-Plan Inc.	0979-53-8880		362-1 Ushigami, Nakatsu City
	Llita Citu		Renesas Semiconductor Kyushu Yamaguchi Co., Ltd., Oita Factory	0979-32-7111		4200 Itouda, Nakatsu City
4	Hita City	59	TDK Corporation, Mikumagawa Factory Asahi Plastic Kogyo Co., Ltd.	0973-24-1111 0972-23-7311	877-0061	3-793-1 Ishii Machi, Hita City 10356-2 Mejima, Saiki City
6	Saiki City	60	Koutec Co., Ltd.	0972-22-5678		
		61	Nagao Seisakusho Co., Ltd.	0972-25-1200	876-1512	2134-24 Oaza Katata, Saiki City
6	Usuki City		J-Devices Corporation			1913-2 Oaza Fukura, Usuki City
0	Kitsuki City		Daihen Technology Institute Takaki-Giken Co., Ltd.	0978-63-4567		1660-7 Oaza Mizoi, Kitsuki City 1680 Azasakai no Tsubo, Oaza Hino, Kitsuki City
			Higashi Kyushu Electric Industry Co.	0978-33-3533		2019 Oaza Shimotakei, Usa City
8	Usa City	66	World Precision Tooling Inc.	0978-37-0287	879-0453	1544-2 Oaza Ueda, Usa City
9	Yufu City		AK System Co., Ltd.	097-582-3311		1474 Otatsu, Shonai Cho, Yufu City
	-		Denken Co., Ltd.			97-1 Oaza Takazaki, Hasama Machi, Yufu City
•	Kunisaki City		Sony Semiconductor Kyushu Corporation, Oita Technology Center USC Corporation, Oita QI Center	0978-72-5730 0978-64-8121		3319-2 Oaza Owara, Kunisaki Machi, Kunisaki City 240 Furuichi, Musashi Machi, Kunisaki City
	Sity		Add Technology	0977-72-9427		9265-1 Oga, Hiji Machi, Hayami-gun
			AK Electronics Co., Ltd.	0977-72-0042	879-1502	1237 Oaza Fujiwara, Hiji Machi, Hayami-gun
		73	Mentor Analog Plus, Ltd	0977-73-0032	879-1502	2497-3 Oaza Fujiwara, Hiji Machi, Hayami-gun
			ELIA Co., Ltd.			799-1 Oaza Toyo-oka Oaza Iwagaki, Hiji Machi, Hayami-gun
		76	Oita Denshi Co., Ltd. Ohkawa Mould Designs & Engineering Co., Ltd.	0977-72-3477		867 Oaza Toyo-oka, Hiji Machi, Hayami-gun 32-2 Oaza Oga, Hiji Machi, Hayami-gun
0	Hiji Town		Kyushu Semiconductor KAW Co., Ltd.			15-10 Kawasaki, Hiji Machi, Hayami-gun
	,		KSK Co., Ltd.			4321-1 Oaza Kawasaki, Hiji Machi, Hayami-gun
			CLI Co., Ltd.	0977-75-6454	879-1502	1910-21 Oaza Fujiwara, Hiji Machi, Hayami-gun
			Texas Instruments Japan Limited, Hiji Plant			4260 Oaza Kawasaki, Hiji Machi, Hayami-gun
			Hiji High-Tech Co., Ltd. Fukumiya Denshi Co., Ltd.			8133 Oaza Oga, Hiji Machi, Hayami-gun 1154-1 Oaza Toyo-oka, Hiji Machi, Hayami-gun
		83	IHUKS Co.	109//-/2-hhh	8/9-1504	19/48-6 Uaza Uga, Hili Machi. Havami-giin
P	Kusu Town		HOKS Co. KCHK Spring Industry Co., Ltd. Fuilta Chemical Industry Co., Ltd.		879-4521	9748-6 Oaza Oga, Hiji Machi, Hayami-gun 500-1 Oaza Ota, Kusu Machi, Kusu-gun 6509-4 Oaza Tobata, Kusu Machi, Kusu-gun

Oita Prefecture Semiconductor Affiliated Company Technology Map

Pro	Process Category				Company (Technological Expertise)					
	Design (Device/Package) 5		5	13 STK Technology (Logic design)	Denken (Substrate package (LGA/BGA, etc.), plastic package (QFP, etc.))	73 Mentor Analog Plus (Analog/DA circuit design, layout design)	79 CLI (Power source control IC planning, circuit design, customer support)	81 Hiji High-Tech (Semiconductor circuit design)		
	Manufacture	Front-end	2	Toshiba Semiconductor & Storage Products Company, Oita Factory (System LSI,Image sensor fabrication)	Texas Instruments Japan (High-voltage, high speed BiCMOS, SiN, HiPOX, SOI wafer processing, etc.)					
acture				13 STK Technology (Package Molds, TF commissions)	Oita Device Technology (DB/ WB/MD/PO processing, ceramic/ specialty packaging, general-purpose IC assembly)	Shimada Electronics Works (Die bonding, wire bonding, molding)	Renesas Semiconductor Kyushu Yamaguchi (Full QFP,SIP line from dicing to shipping, high- precision loop management)	J-Devices (Lead packaging /BGA assembly, taping (various))		
Semiconductor Manufacture		Back-end (Overall)	11	Kyushu Semiconductor KAW (Dicing, die bonding, wire bonding, molding)	Carrier Denken (Substrate package (LGA/BGA, etc.), plastic package (QFP, etc.))	Sony Semiconductor Kyushu Corporation (LSI packaging, SiP assembly manufacture)	75 Oita Denshi (logic LSI back-end processing/assembly processing)	Texas Instruments Japan (Backgrinding, dicing, die bonding, Low-k wire bonding, molding, etc)		
Semico				Hiji High-Tech (Dicing, die bonding, wire bonding, molding, etc.)						
4		Back-end (Component- specific)	5	STK Technology (Visual inspection, taping, packing operations commissions)	Shell Electronics (BGA repair and ball soldering)	Takaki-Giken (SOP, QFP, BGA, etc. taping, packaging dehumidification, microscope visual inspection, BGA substrate machine- assisted visual inspection)	Higashi Kyushu Electric Industry (leadframe plating, TF and marking process)	72 AK Electronics (IC chip cutting, visual inspection for sorting, taping)		
	Evaluation (Testing)	Wafer Test	5	STK Technology (Full-process contracting from production program development and manufacture to evaluation analysis, wafer testing commissions, test engineering services)	Toshiba Semiconductor & Storage Products Company, Oita Factory (LSI wafer high- speed testing)	J-Devices (Various kinds of wafer testing)	Kyushu Semiconductor KAW (Wafer electrical property testing)	Texas Instruments Japan (Technology for automation of networked production data)		

Pro	Process Category		No. of Companies	Company (Technological Expertise)					
				13 STK Technology (Full-process contracting from production program development and manufacture to evaluation analysis, final testing commissions, test engineering services)	18 Oita Device Technology (marking/TF/testing/ visual inspection/burn-in/ taping)	Takaki Tools & Materials (ball inspection, visual inspection)	Renesas Semiconductor Kyushu Yamaguchi (High-speed multi-function measurement technology, capacity for small-batch manufacture of diverse products)	Shimada Electronics Works (Specialized characterization testing for light sensors, etc.)	
	Evaluation (Testing)		12	G2 J-Devices(lead packaging /BGA/WLCSP testing)	77 Kyushu Semiconductor KAW (Electrical property testing (packaging))	Denken (Logic testing)	74 ELIA (Testing specification design, program and board development)	75 Oita Denshi (Logic LSI final testing, 8-piece parallel testing)	
				Texas Instruments Japan (Testing machinery maintenance and repair technology)	Hiji High-Tech (Program development, characteristics evaluation, mass-production testing, etc.)				
	Analysis 13			STK Technology (Trial production, mass production analysis, other analysis)	Oita Device Technology (X-ray nondestructive inspection/SEM examination)	Sumika Chemical Analysis Service (Morphological examination, surface analysis, clean room efficacy evaluation, chemical impurity analysis)	Toshiba Information Systems Technology (Wafer yield improvement analysis, wafer defect location analysis)	Toshiba Semiconductor & Storage Products Company, Oita Factory (Possesses various evaluation and analytical technologies)	
A Semiconductor Manufacture			42 Nittetsu Oita Techno Support (Defect analysis, contamination analysis, topography analysis, particle analysis)	J-Devices (Possesses various general purpose analytical equipment such as a SAM and a SEM)	Denken (X-ray, SAT, SEM, EDX, decap, V/I, deprocessing, EMMI, OBIRCH, Xsection, liquid crystals, laser displacement metering, repackaging, temperature property evaluation, BGA ball restoration, etc.)	TO USC Corporation, Oita QI Center (package opening, chemical analysis, examination)	73 Mentor Analog Plus (Circuit design evaluation analysis)		
			74 ELIA (Testing specification design, evaluation board development and testing, evaluation reporting)	Texas Instruments Japan (Evaluation of the mechanical and thermal properties of IC packaging through computer simulation)	81 Hiji High-Tech (Semiconductor measurement systems)				
	Reliabilii	Reliability Testing 7		13 STK Technology (Burn-in commissions, test program development and evaluation)	18 Oita Device Technology (Temperature cycle test(TCT)/Pressure cooker test (PCT))	Sumika Chemical Analysis Service (Environmental testing, nondestructive inspection, package opening, electrical testing)	Toshiba Semiconductor & Storage Products Company, Oita Factory (Possesses various reliability testing facilities)	Denken (Environmental testing, solder thermal resistance evaluation, board mounting evaluation, ESD-MM/HBM/CDM evaluation, latchup evaluation, burn-in, etc.)	
				Texas Instruments Japan (IC packaging environmental testing technology)	Hiji High-Tech (Semiconductor testing systems)				
		Human Resources/		Willtec Kyushu (Contracting of semiconductor manufacture front-end, testing, and shipping processes)	Krone (Semiconductor machinery assembly, liquid crystal testing machinery assembly, miscellaneous machinery assembly, piping, and wiring)	Copan (Human resources support to each factory)	Kyushu Partner's (Manufacturing and defect analysis, quality assurance, contracting and dispatch for manufacturing machinery assembly)	T-Plan (Introduction and dispatch of specialized technicians)	
	Conti	racting	7	Denken (Specialized dispatch (analysts, reliability testers), contracting (analysis, reliability evaluation), and other services)	71 Add Technology (Comprehensive work contracting for semiconductor electronic circuit design, evaluation, and analysis)				

Р	Process Category		No. of Companies	Company (Technological Expertise)				
		Direct Materials (Leadframes, etc.)	1	NYS Precision (Leadframe (downset cutting, visual inspection))				
	Material Manufacture	Indirect Materials (Gases, solutions, tape, packing,	6	9 Ueki Corporation (Gases, related instruments, metal materials)	24 Kyushu Yozai (Petrochemical solvent manufacture and sales)	35 Takaki Tools & Materials (Carrier tape molding)	TDK (Applicable films such as clear conductive films)	Asahi Plastic Kogyo (Plastic irregular extrusion shape forming, shipping tubes for semiconductors packages and electronic components, general plastic extrusion manufacture)
		etc.)		84 KCHK Spring Industry (Metal fabrication)				
	Machine Manufacture	Front-end	2	Ulvac Techno Kyushu (Comprehensive vacuum technology, semiconductor manufacturing instruments, vacuum device manufacture)	12 Threedyne (Semiconductor wafer cleaning machines)			
cture		Back-end	3	6 Ishii Tool & Engineering (Soft pressing equipped lead processing machines (TF), laser marking, handlers, etc.)	Takaki Tools & Materials (Taping machines, visual inspection machines, laser marking machines, general machinery)	76 Ohkawa Mould Designs & Engineering (Machines for visual inspection using 3-D image processing)		
or Manufac		Evaluation Process (Testers, probers, handlers)	5	STK Technology (Burn-in testers, IC handling machines)	30 Shell Electronics (IC chip visual inspection machines)	35 Takaki Tools & Materials (Handling machines, semiconductor inspection machines)	Todaka (Taping machines, visual inspection machines, laser marking machines, general machinery)	Denken (OS testers, IC handlers, LD testers, DC testers, visual inspection machines, etc.)
elated to Semiconductor Manufacture	Machine Manufacture	Misc. Machines	10	15 Eto Manufacturing (Design and manufacture of mechatronics instruments, precision inspection instruments, etc.)	23 Kansetsu (Designing semiconductor manufacture machines (especially cleaning machines))	30 Shell Electronics (Clean booth manufacture)	33 Threedyne (Semiconductor manufacture related equipment)	35 Takaki Tools & Materials (Customized development)
			10	36 Tani Kogyo (Environmental related equipment, machine development, design, and construction)	41 Todaka (Handling machine special order manufacture)	U.S.I (Measurement systems development and manufacture)	Daihen Technology Institute (Design and assembly of automated machinery and automatic particle free transport machines)	AK System (Commission production of air conditioning related machines, automatic transport machines, labor saving machines, etc.)
Technologies R		Tools (Probe cards, etc.)		Aberuf (Probe cards, performance board design, high-reliability sockets)	13 STK Technology (Burn-in board design and production, change kit design and manufacture)	27 Copan (Tools, labor saving instrument semiconductors)	Takaki Tools & Materials (Burn-in boards, inserter/extractor machines)	41 Todaka (Tools design and development)
B Tech			11	Micronics Japan (Probe card manufacture, probe card inspection machines, wafer prober, sockets)	World Precision Tooling (Electrode manufacture and sales)	Denken (Burn-in boards, Manual measurement tool development, etc.)	USC Corporation, Oita QI Center (Aging boards, metal molds)	T4 ELIA (Development of general testing boards, measurement sockets, and tools)
	Parts/Tools Manufacture			81 Hiji High-Tech (Development of performance boards and manual measurement tools)				
		Machine	chine 10	Agawa Mekki (Wet electroplating, non- ferrous metal surface processing)	Adachi Chemical Plants (Welding, piping, and can manufacturing technologies)	STK Technology (Precision sheet metal work, machining)	Kamimaru (Gas supply machine design and manufacture, gas piping manufacture)	Takaki Tools & Materials (Planning, processing, and surfacing of parts, precision sheet metal work, machine frames, etc.)
		Parts	. •	37 TEC Engineering (Comprehensive gas supply equipment)	44 Micronics Japan (Metallic rod processing including W, Re-W, and Be-Cu, ceramic plate thin film lamination, sockets)	61 Nagao Seisakusho (Precision sheet metal work)	76 Ohkawa Mould Designs & Engineering (Plastic molded parts manufacture for semiconductors)	85 Fujita Chemical Industry (Precision plastic molding)
		Metal Mold Manufacture		6 Ishii Tool & Engineering (Precision metal molding)	66 World Precision Tooling (Metal molding precision parts)	76 Ohkawa Mould Designs & Engineering (Metal mold design and manufacture)	78 KSK (Metal mold parts manufacture for TF machines (Lead pitch with precision of 0.3, ± 0.001 mm))	

Pro	Process Category		No. of Companies	Company (Technological Expertise)				
Semiconductor Manufacture	Analysis		2	A2 Nittetsu Oita Techno Support (High temperature/ low temperature tensile testing, fatigue testing, wear testing, chemical analysis, surface formation measurement)	Sumika Chemical Analysis Service (Formation examination, surface analysis, clean room efficacy evaluation, chemical impurity analysis)			
	Reliability		3	32 Sumika Chemical Analysis Service (Environmental testing, nondestructive inspection, package opening, electrical testing)	35 Takaki Tools & Materials (Capable of micron- level accurate parts management)	USC Corporation, Oita OI Center (Reliability testing and environmental testing (high/low temperature, high/low humidity, temperature cycling, etc.), mechanical strength testing (vibration, shock, dropping))		
Related to Se	Maintenance	Manufacture Machinery Cleaning	5	NYS Precision (Precision cleaning of semiconductor manufacture machine parts)	Kamimaru (Cleaning of semiconductor manufacture machine parts)	25 Kuritec Service (Precision cleaning of semiconductor manufacture machine parts)	Neos (Precision cleaning of manufacture machine internal parts (dust reduction in vacuum chamber techniques))	Higashi Kyushu Electric Industry (Burn-in board and socket cleaning, burn- in board inspection and repair, cleaning of tray magazines, etc.)
Technologies Related to		Misc.	5	5 Ulvac Techno Kyushu (Comprehensive vacuum technology, semiconductor device manufacture machine maintenance, vacuum instrument maintenance)	17 Oita General Service (Precision cleaning of clean suits, IC trays, etc.)	33 Threedyne (Contract maintenance for automated instruments)	46 Network (Semiconductor related machine maintenance)	49 Horiba Techno Service (Analytical instrument maintenance)
В	N	∕lisc.	5	16 NYS Precision (Semiconductor manufacture materials sales)	31 Suzuki (Source and indirect materials supply firm)	Takaki Tools & Materials (Procurement of processed resin products, specialized materials, etc.)	Pleson (Comprehensive semiconductor manufacture machine implementation technologies)	Koutec (Dry ice cleaning)
	Board design and manufacture		4	Aberuf (50 Ω impedance matching board design and manufacture)	6 Ishii Tool & Engineering (Control board manufacture)	S-Craft (High-speed transmission PCB design)	30 Shell Electronics (PCB design)	
rd Set)	Mounting		9	4 Aberuf (Test board assembly)	30 Shell Electronics (PCB mounting, lead- free compliant reflow machines installed)	35 Takaki Tools & Materials (Burn-in boards, inserter/extractor machines)	47 Britec (Probe card processing, PCB mounting)	Shinyei Technology (SMT/RA/AX mounting, various assembly)
Mounting(Board				DENKEN (Power modules, fingerprint sensors, AC adapters, etc.)	Sony Semiconductor Kyushu (Semiconductor packaging)	Fukumiya Denshi (Board mount and semiconductor machines assembly)	HOKS (Lead-free compliance, SMT technology (BGA, CSP, 0.4 pitch QFP, 0603 chips))	
C Mount	Evaluation		4	Nittetsu Oita Techno Support (Joint interface analysis, soldering evaluation, packaging opening and testing, destructive analysis, heat cycle testing)	Shell Electronics (Electrical inspection after PCB mounting)	DENKEN (CMOS sensors, power modules, fingerprint sensors, etc.)	Sony Semiconductor Kyushu (Packaging product testing)	
	Reliability		1	68 DENKEN (CMOS sensors, power modules, fingerprint sensors, etc.)				
Software	Integration Systems		9	7 InfoWave (Web systems design and development, image processing technologies)	SS-Avenue (Evaluation programs)	13 STK Technology (Communications integration systems)	28 Sard Electron (Machine development (Wiring design, software development), control instrument development)	Zynas (Embedding and control application development)
S O				Mobile Create (System design and development)	DENKEN (H8, SH, etc. microcomputer hardware and software development)	74 ELIA (Custom-designed system suppont)	Hiji High-Tech (Embedded systems (hardware, software) development)	

F	Process Category		No. of Companies	Company (Technological Expertise)					
E Miscellaneous	L	_CD Display-related	3	32 Sumika Chemical Analysis Service (Formation examination, surface analysis, clean room efficacy evaluation, chemical impurity analysis)	Micronics Japan (Panel probing, automated alignment, contact technology, panel electrode cutting, image processing inspection technology)	68 DENKEN (Aging machines, FC, etc.)			
	20	Solar Cell-related	2	YAC (Solar cell-related machine development and manufacture)	68 DENKEN (Solar cell inspection machine development and manufacture)				
		Recycling	2	Daiso (Recycling an disposal, from planning to execution)	Tobu Kaihatsu (Disassembly, industrial waste processing)				
		Semiconductor Manufacturing Machine Sales/ Representation	3	Advantest (Memory device, SOC test machine, and test handler manufacture and sales)	SMC (Manufacture and sales of temperature control products such as Thermo-chillers and Thermo-controllers, and air pressure driving devices)	Espec Kyushu (Semiconductor manufacture machine sales, inspection and reliability evaluation machine sales)			
		Misc.	4	Otsuka Diesel (Diesel engine and dynamo sales and maintenance)	20 ODDS (Semiconductor technology literature writing, translation, and software development)	Kawanodenki (Design and production of power distribution boards, panelboards, and control boards, etc.)	43 Nippon Express (Logistics, liquid crystal/semiconductor manufacture machine transportation and installation)		

Manufacturing Process

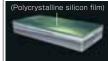
Oxidization

Wafers are placed in a high-temperature furnace while exposed to an oxidizing atmosphere to form an oxide film on the wafer's surface.



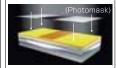
2 Thin Film Formation

Using the chemical vapor deposition (CVD) method, gases react chemically in CVD chamber to form a polycrystalline silicon film over the oxide film.



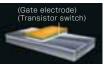
3 Photolithography

In photolithography, a photomask is used to form a resist pattern for circuits on the surface of the wafer.



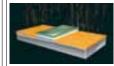
4 Dry Etching

lons of reactive gases in a plasma state are shot in pulses at the wafer using electric field, etching along the resist pattern for aluminum film or other materials.



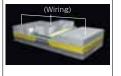
5 implantation

Impurities are ionized in a vacuum and electromagnetically charged to energies of tens or hundreds of keV which are then implanted into the surface of the wafer.



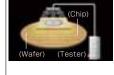
6 Wiring

An aluminum "target" (source) is sputtered with inert gas plasma and deposited as a thin metallic film onto the wafer to form circuitry wiring.



Wafer Testing

Each chip on the wafer is tested, viable chips are sorted from defective chips, and defective chips are marked in memory data



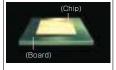
8 Dicing

Each chip is separated from the wafer using a diamond blade.



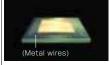
9 Mounting

The chip is mounted onto a specific location of board.



10 Ronding

The chip is connected to the board using gold wires and other materials.



Molding

The chip is sealed in resin or other package materials.



12 Product Inspection

Tests are performed, such as electronic property inspection and visual inspection, and defective products are removed.





Contact

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